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Dimensions	
Chip Size	2220
L	5.69mm +/-0.41mm (0.224 in +/-0.016 in)
W	5mm +/-0.41mm (0.197 in +/-0.016 in)
T	2.79mm MAX (0.11 in MAX)
B	0.64mm +/-0.46mm (0.025 in +/-0.018 in)

Packaging Specifications	
Packaging	Waffle
Packaging Quantity	20

General Information	
Series	SMD MIL BP PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	Yes
Termination	Gold
Failure Rate	N/A
Qualifications	MIL-PRF-32535 T-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.01 uF
Capacitance Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Dissipation Factor	0.15% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOHms

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